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Part Number: [73780-1233](#)
Status: **Active**
Overview: [HDM®](#)
Description: HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 144 Circuits, Mounted Height 13.00mm, Pin Length 2.00mm, Solder Tail

Documents:

3D Model	Test Summary TS-73670-990 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)
Product Specification PS-73780-999 (PDF)	

Agency Certification

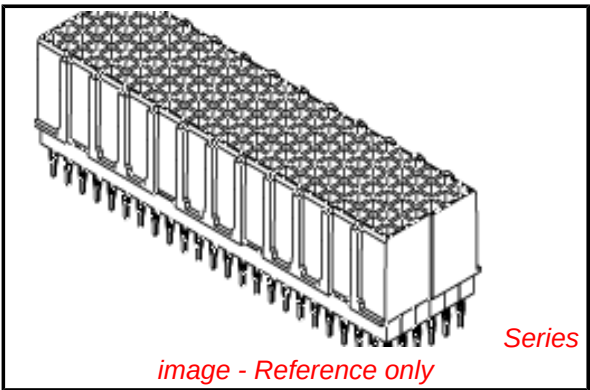
UL	E29179
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General

Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	HDM®
Product Name	HDM®
Style	N/A
UPC	800753003545

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	20.030/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	2.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen

China RoHS



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environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73780Series](#)

Mates With

HDM® Board-to-Board Backplane Header
[73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) ,
[73944](#) , [74349](#) , [74428](#). HDM® Board-to-
Board Stacking Header [73769](#) , [73770](#) ,
[73782](#) , [73783](#) , [73771](#)

Termination Interface: Style	Through Hole
Electrical	
Current - Maximum per Contact	15A, 1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Product Specification	PS-73780-999
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990

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This document was generated on 07/25/2014

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